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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/643,684	08/18/2003	Thomas Kenny	COOL-01600	4600
7590 01/14/2005			EXAMINER	
Thomas B. Haverstock			MCKINNON, TERRELL L	
HAVERSTOCK & OWENS LLP 162 North Wolfe Road			ART UNIT	PAPER NUMBER
Sunnyvale, CA 94086			3743	
			DATE MAILED: 01/14/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
`	10/643,684	KENNY ET AL.			
Office Action Summary	Examiner	Art Unit			
	Terrell L Mckinnon	3743			
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address			
A SHORTENED STATUTORY PERIOD FOR REPL' THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl - If NO period for reply is specified above, the maximum statutory period of the period for reply within the set or extended period for reply will, by statute any reply received by the Office later than three months after the mailing tearned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be timely within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. O (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on 12 C	October 2004.				
· _ ·	action is non-final.				
3) Since this application is in condition for allowa	,—-				
Disposition of Claims					
4) ⊠ Claim(s) <u>1-56</u> is/are pending in the application 4a) Of the above claim(s) is/are withdray 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) <u>55 and 56</u> is/are rejected. 7) ⊠ Claim(s) <u>29 and 54</u> is/are objected to. 8) □ Claim(s) are subject to restriction and/or	wn from consideration.				
Application Papers					
9) The specification is objected to by the Examine 10) The drawing(s) filed on 18 August 2003 is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex	a)⊠ accepted or b)⊡ objected t drawing(s) be held in abeyance. See tion is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).			
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	ts have been received. ts have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage			
Attachment(s) 1) Notice of References Cited (PTO-892)	. 4) 🔲 Interview Summary	(PTO-413)			
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 	Paper No(s)/Mail Da				

Art Unit: 3743

Response to Amendment

Receipt is acknowledged of applicant's amendment filed October 12, 2004.

Claims 1-54 and newly added claims 55-56 are pending and an action on the merits is as follows.

Applicant's arguments with respect to claims 1-54 have been considered but are most in view of the new grounds of rejection.

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-5, 7-10, 15, 19-21, 26, 27, 30-34, 36-39, 44 and 48-52 rejected under 35 U.S.C. 103(a) as being unpatentable over Benett et al. (U.S. 5,548,605) in view of Tsai et al. (U.S. 6,206,022).

Benett discloses a monolithic micro-channel heat sink comprising all of the applicant's claimed and disclosed limitations of the instant invention.

Benett fails to disclose each trench having a substantially planar floor.

3. However, Tsai teaches the use of an integrated flow controller module wherein each trench having a substantially planar floor.

Art Unit: 3743

Given the teachings of Tsai, it would have been obvious to one of ordinary skill in the art at the time of the invention to modify the heat sink of Benett with each trench having a substantially planar floor.

Doing so would provide an alternative arrangement for improving providing thermal fluid flow.

4. Claims 6, 28, 35 and 53 are rejected under 35 U.S.C. 103(a) as being unpatentable over Benett et al. (U.S. 5,548,605) in view of Tsai et al. (U.S. 6,206,022) as applied to claims above, and further in view of DeBoer et al. (U.S. 6,632,71).

Benett's invention, as modified by Tsai, discloses all of the claimed limitations from above except for the etchant comprises tetramethyl ammonium hydroxide (TMAH); and wherein the narrowing trench has a depth:width aspect ratio of at least approximately 10:1.

5. However, DoBoer teaches etchant comprises tetramethyl ammonium hydroxide (TMAH); and wherein the narrowing trench has a depth:width aspect ratio of at least approximately 10:1 (column 9, lines 40-50).

Given the teachings of DoBoer, it would have been obvious to one of ordinary skill in the art at the time of the invention to modify the heat sink of Benett with the etchant comprises tetramethyl ammonium hydroxide (TMAH); and wherein the narrowing trench has a depth:width aspect ratio of at least approximately 10:1.

Doing so would provide an alternative etchant for silicon chip cooling.

Art Unit: 3743

6. Claims 16-18, 22-25 and 45-47 are rejected under 35 U.S.C. 103(a) as being unpatentable over Benett et al. (U.S. 5,548,605) in view of DeBoer et al. (U.S. 6,632,71) as applied to claims above, and further in view of Zingher (U.S. 5,310,440).

Page 4

Benett's invention discloses all of the claimed limitations from above except for the manifold layer comprising a first plurality of interconnected hollow fingers and a second plurality of interconnected hollow fingers, the first plurality of interconnected hollow fingers providing flow paths to the one or more first apertures and the second plurality of interconnected hollow fingers providing flow paths from the one or more second apertures; the first plurality of interconnected hollow fingers and the second plurality of interconnected hollow fingers lie substantially in a single plane; coupling a pump to the first plurality of interconnected hollow fingers; the cooling material comprises a liquid water; and the cooling material comprises a liquid/vapor mixture.

7. However, Zingher teaches a manifold layer comprising a first plurality of interconnected hollow fingers and a second plurality of interconnected hollow fingers, the first plurality of interconnected hollow fingers providing flow paths to the one or more first apertures and the second plurality of interconnected hollow fingers providing flow paths from the one or more second apertures; the first plurality of interconnected hollow fingers and the second plurality of interconnected hollow fingers lie substantially in a single plane; coupling a pump to the first plurality of interconnected hollow fingers; the cooling material comprises a liquid water; and the cooling material comprises a liquid/vapor mixture.

Given the teachings of Zingher, it would have been obvious to one of ordinary skill in the art at the time of the invention to further modify the micro-channel heat sink of Benett with a manifold layer comprising a first plurality of interconnected hollow fingers and a second plurality of interconnected hollow fingers, the first plurality of interconnected hollow fingers providing flow paths to the one or more first apertures and the second plurality of interconnected hollow fingers providing flow paths from the one or more second apertures; the first plurality of interconnected hollow fingers and the second plurality of interconnected hollow fingers lie substantially in a single plane; coupling a pump to the first plurality of interconnected hollow fingers; the cooling material comprises a liquid water; and the cooling material comprises a liquid/vapor mixture.

Doing so would provide cooling flow paths for efficiently controlling the temperature of the heat sink.

8. Claims 11-14 and 40-43 are rejected under 35 U.S.C. 103(a) as being unpatentable over Benett et al. (U.S. 5,548,605) in view of DeBoer et al. (U.S. 6,632,71) as applied to claims above, and further in view of Newton et al. (U.S. 6,437,981).

Benett's invention discloses all of the claimed limitations from above except for manifold and interface layers being bonded by adhesively bonding; anodic bonding; thermal fusing; and eutectucally bonding to each other.

9. However, Newton teaches a pluralities of composite components being bonded by anodic bonding; the pluralities of composite components are bonded with a

Art Unit: 3743

thermoplastic bonding sheet by thermal fusing; and silicon and glass composite components bonded to each other (Fig. 17B).

Given the teachings of Netwon, it would have been obvious to one of ordinary skill in the art at the time of the invention to furthermore modify the heat sink of Benett with the manifold and interface layers being bonded by adhesively bonding; anodic bonding; thermal fusing; and eutectucally bonding to each other.

Doing so would provide a reliable and thermally secure connection between the manifold and interface layers.

Allowable Subject Matter

- 10. Claims 55 and 56 are allowed.
- 11. Claims 29 and 54 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Response to Arguments

Applicant's arguments filed October 12, 2004 have been fully considered but they are not persuasive.

Applicant's states, Benett fails to disclose or suggest each trench has a substantially planar floor, and each aperture is positioned on one side of a narrowing trench.

Benett invention, as modified by Tsai, discloses each trench has a substantially planar floor, and each aperture is positioned on one side of a narrowing trench.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Terrell L Mckinnon whose telephone number is 703-305-0059. The examiner can normally be reached on Monday -Thursday and every other Friday.

Application/Control Number: 10/643,684 Page 8

Art Unit: 3743

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Henry Bennett can be reached on 308-0101. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Terrell L Mckinnon Primary Examiner Art Unit 3743 August 6, 2004